

ABSTRACT OF THE INVENTION

An interposer for interconnection between microelectronic circuit panels has contacts at its surfaces. Each contact extends from a central conductor, and has a peripheral portion adapted to contract radially inwardly toward the central conductor response to a force applied by a contact pad defining a central hole on the engaged circuit panel. Thus, when the circuit panels are compressed with the interposers, the contacts contract radially inwardly and wipe across the pads. The wiping action facilitates bonding of the contacts to the pads, as by friction welding, or by a conductive bonding material carried on the contacts themselves.

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